NOTES

1. MATERIALS:
   LEAD FRAME: COPPER 194FH, THK = 0.203 ± 0.008
   BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QUIK-PAK FOR DETAILS.

2. FINISH:
   LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1,
   200 TO 300 MICROINCHES (2.5um-7.6um) THICK.
   GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1
   (40 TO 80 MICROINCHES (1um-2um) THICK).
   BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)

3. PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.

4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES
   AND CORNERS = 0.25mm MAX.

5. PACKAGE CONFORMS TO JEDEC MO-220

DIMENSIONS ARE IN MILLIMETERS
TOLERANCES ARE:
   ANGULAR: ±0.5 degree
   .X = ±0.76
   .XX = ±0.25
   .XXX = ±0.13
   .XXXX = ±0.01

MATERIAL
   SEE NOTE 1

FINISH
   SEE NOTE 2

COMMENTS

DRAWN
D. Abbe 8/15/11

CHECKED
S. Swen 8/15/11

ENG APPR
S. Swen 8/15/11

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SHEET 1 OF 1

SCALE: 10:1 WEIGHT: 500417

QP-QFN24-5MM-0.65MM